

Features

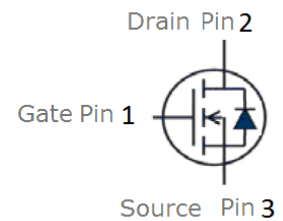
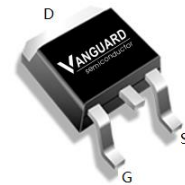
- N-Channel
- Enhancement mode
- Very low on-resistance @ $V_{GS}=4.5\text{ V}$
- Fast Switching
- 100% Avalanche test
- Pb-free lead plating; RoHS compliant



Part ID	Package Type	Marking	Tape and reel information
VSD140N15MD	TO-252	140N15M	2500pcs/reel

V_{DS}	150	V
$R_{DS(on),typ@VGS=10V}$	125	m Ω
$R_{DS(on),typ@VGS=4.5V}$	115	m Ω
I_D	10	A

TO-252



Maximum ratings, at $T_j=25\text{ }^\circ\text{C}$, unless otherwise specified

Symbol	Parameter	Rating	Unit	
$V_{(BR)DSS}$	Drain-Source breakdown voltage	150	V	
V_{GS}	Gate-Source voltage	± 20	V	
I_D	Continuous drain current @ $V_{GS}=10\text{ V}$	$T_C=25^\circ\text{C}$	10	A
		$T_A=100^\circ\text{C}$	6.4	A
I_{DM}	Pulse drain current tested ①	$T_C=25^\circ\text{C}$	25	A
P_D	Maximum power dissipation	$T_C=25^\circ\text{C}$	50	W
I_S	Diode Continuous Forward Current	$T_C=25^\circ\text{C}$	10	A
EAS	Avalanche energy, single pulsed ③	$I_D=3\text{ A}$	2.25	mJ
T_J	Maximum Junction Temperature	175	$^\circ\text{C}$	
T_{STG}	Storage temperature range	-55 to 175	$^\circ\text{C}$	
Thermal characteristics				
$R_{\theta JA}$	Thermal Resistance-Junction to Ambient	100	$^\circ\text{C/W}$	
$R_{\theta JC}$	Thermal Resistance-Junction to Case	3.0	$^\circ\text{C/W}$	

Typical Electrical Characteristics

Symbol	Parameter	Condition	Min.	Typ.	Max.	Unit
Static Electrical Characteristics @ T_J = 25°C (unless otherwise stated)						
V _{(BR)DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =250μA	150	--	--	V
I _{DSS}	Zero Gate Voltage Drain Current(Tc=25°C)	V _{DS} =150V, V _{GS} =0V	--	--	1	μA
	Zero Gate Voltage Drain Current(Tc=125°C)	V _{DS} =150V, V _{GS} =0V	--	--	100	μA
I _{GSS}	Gate-Body Leakage Current	V _{GS} =±20V, V _{DS} =0V	--	--	±100	nA
V _{GS(TH)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =250μA	1.3	1.8	2.4	V
R _{DS(ON)}	Drain-Source On-State Resistance②	V _{GS} =10V, I _D =10A	--	125	140	mΩ
R _{DS(ON)}	Drain-Source On-State Resistance②	V _{GS} =4.5V, I _D =4A	--	115	140	mΩ
Dynamic Electrical Characteristics @ T_J = 25°C (unless otherwise stated)						
C _{iss}	Input Capacitance	V _{DS} =75V, V _{GS} =0V, f=1MHz	--	1780	--	pF
C _{oss}	Output Capacitance		--	165	--	pF
C _{rss}	Reverse Transfer Capacitance		--	85	--	pF
Q _g	Total Gate Charge	V _{DS} =75V, I _D =6A, V _{GS} =10V	--	39	--	nC
Q _{gs}	Gate-Source Charge		--	10	--	nC
Q _{gd}	Gate-Drain Charge		--	13	--	nC
Switching Characteristics						
t _{d(on)}	Turn-on Delay Time	V _{DD} =75V, I _D =1A, R _G =6.8Ω, V _{GS} =4.5V	--	18	--	nS
t _r	Turn-on Rise Time		--	10	--	nS
t _{d(off)}	Turn-Off Delay Time		--	30	--	nS
t _f	Turn-Off Fall Time		--	6	--	nS
Source- Drain Diode Characteristics @ T_J = 25°C (unless otherwise stated)						
V _{SD}	Forward on voltage	I _{SD} =10 A, V _{GS} =0V	--	0.84	1.20	V
t _{rr}	Reverse Recovery Time	T _J =25°C, I _{sd} =4A, V _{GS} =0V	--	45	--	nS
Q _{rr}	Reverse Recovery Charge	di/dt=100A/μs		385		nC

NOTE:

- ① Repetitive rating; pulse width limited by max. junction temperature
- ② Pulse width ≤ 300μs; duty cycle ≤ 2%.
- ③ Limited by T_{Jmax}, starting T_J = 25°C, L = 0.5mH, R_G = 25Ω, I_{AS} = 3A, V_{GS} = 10V. Part not recommended for use above this value



Typical Characteristics

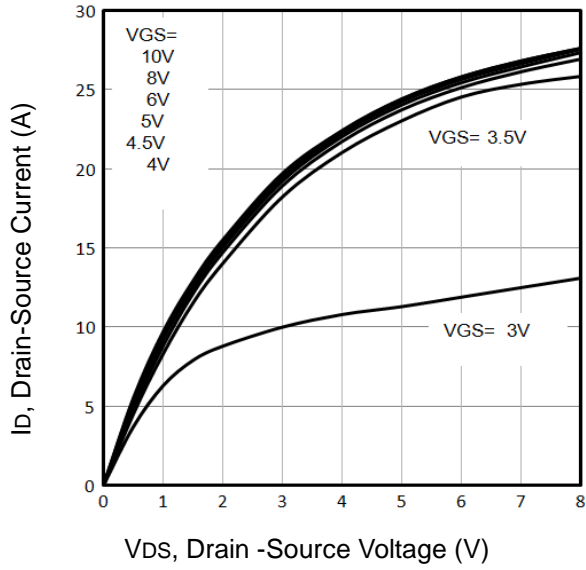


Fig1. Typical Output Characteristics

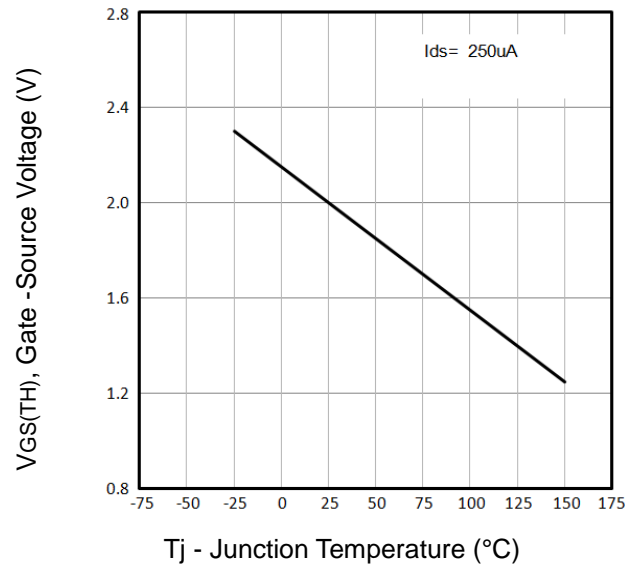


Fig2. Threshold Voltage Vs. Temperature

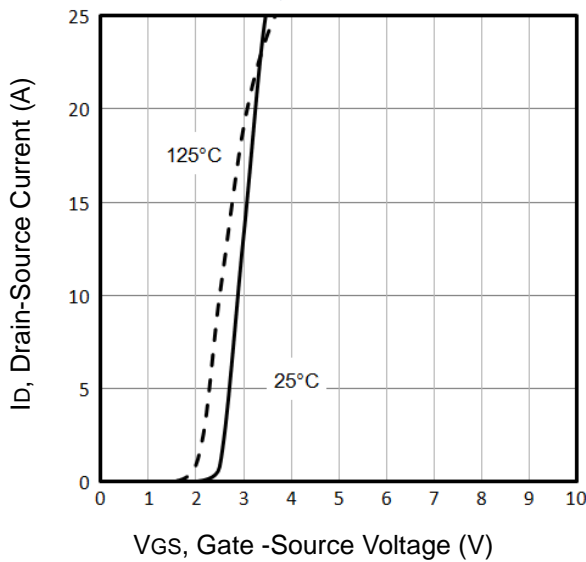


Fig3. Typical Transfer Characteristics

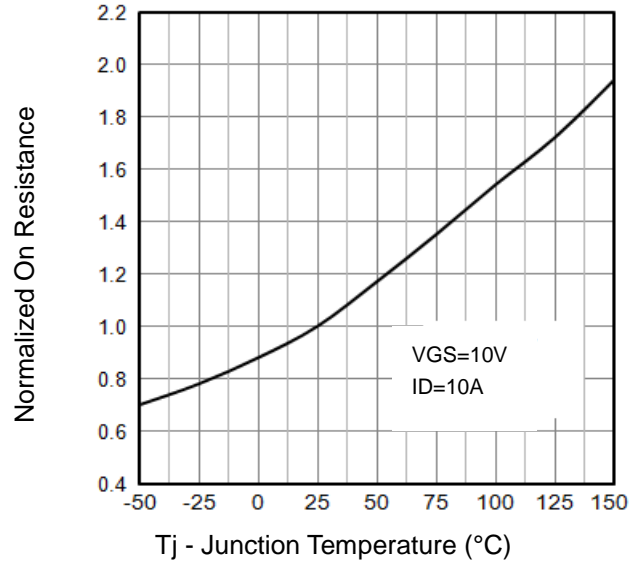


Fig4. Normalized On-Resistance Vs. Temperature

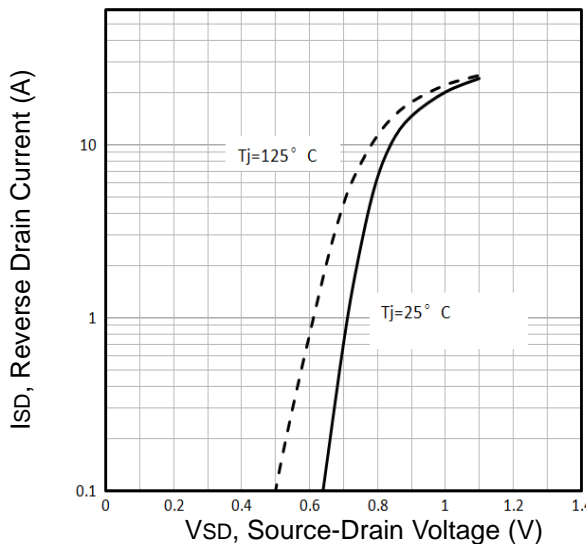


Fig5. Typical Source-Drain Diode Forward Voltage

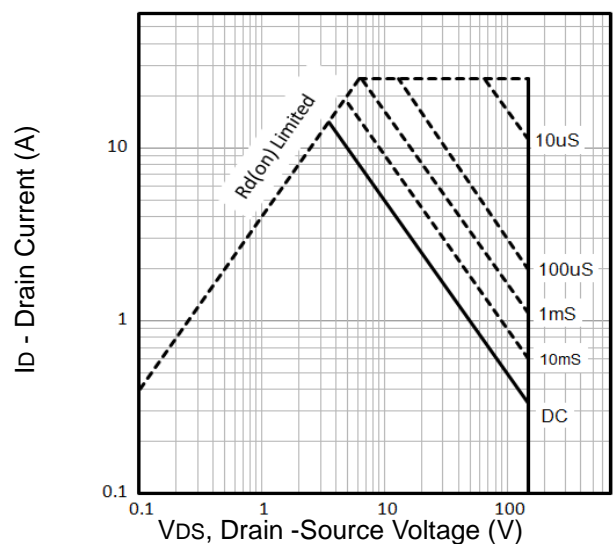


Fig6. Maximum Safe Operating Area

Typical Characteristics

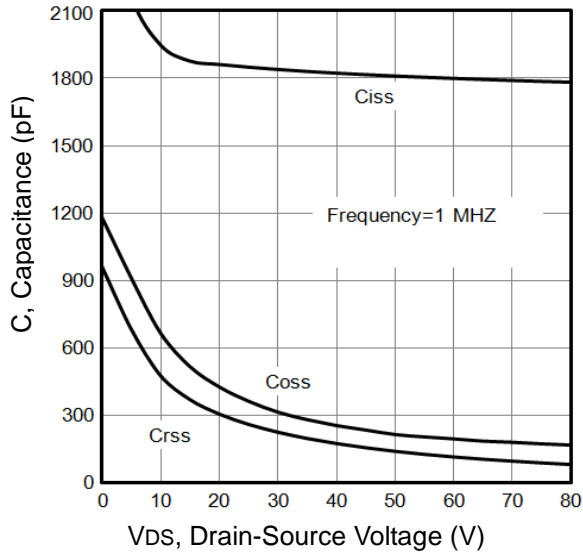


Fig7. Typical Capacitance Vs. Drain-Source Voltage

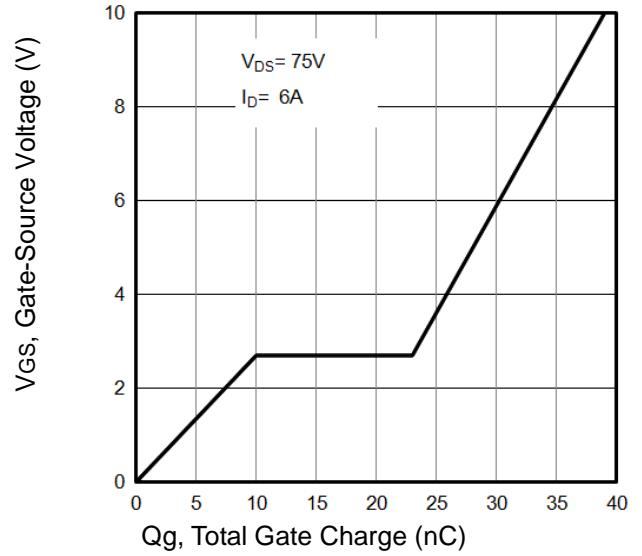


Fig8. Typical Gate Charge Vs. Gate-Source Voltage

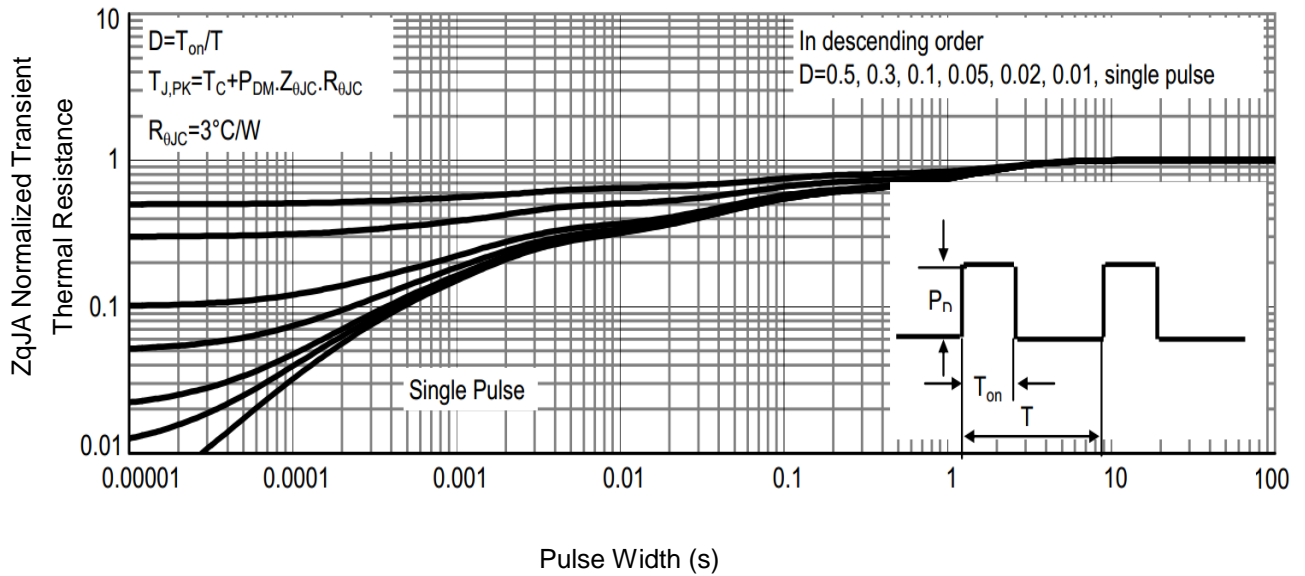


Figure 9: Normalized Maximum Transient Thermal

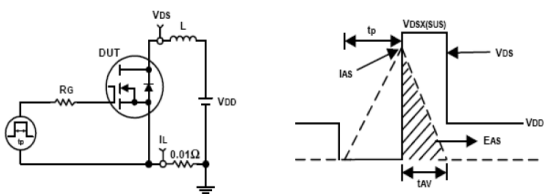


Fig10. Unclamped Inductive Test Circuit and waveforms

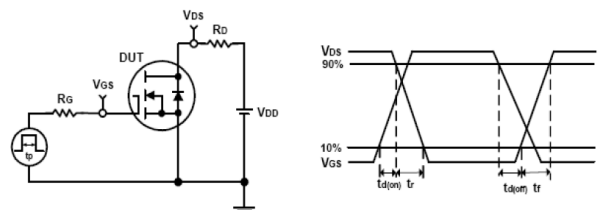
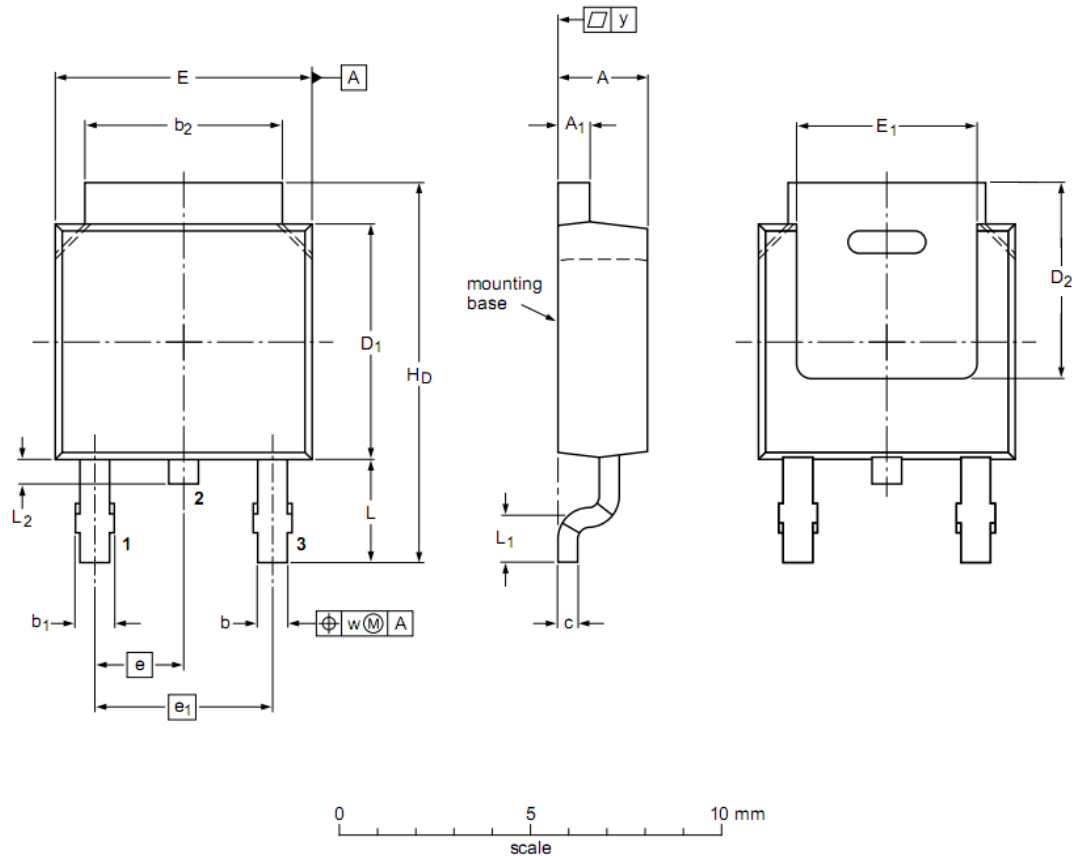


Fig11. Switching Time Test Circuit and waveforms



TO-252 Package Outline Data



Symbol	Dimensions (unit: mm)		
	Min	Typ	Max
A	2.20	2.30	2.38
A ₁	0.46	0.50	0.63
b	0.64	0.76	0.89
b ₁	0.77	0.85	1.14
b ₂	5.00	5.33	5.46
c	0.458	0.508	0.558
D ₁	5.98	6.10	6.223
D ₂	5.21	--	--
E	6.40	6.60	6.731
E ₁	4.40	--	--
e	2.286 BSC		
e ₁	--	4.57	--
H _D	9.40	10.00	10.40
L	2.743 REF		
L ₁	1.40	1.52	1.77
L ₂	0.50	0.80	1.01
w	--	0.20	--
y	--	--	0.20

Notes:

1. Refer to JEDEC TO-252 variation AA
2. Dimension "E" does NOT include mold flash, protrusions or gate burrs. Mold flash, protrusions or gate burrs shall not exceed 0.1524mm per side.
3. Dimension "D1" does NOT include interlead flash or protrusion. Interlead flash or protrusion shall not exceed 0.1524mm per end.

Customer Service

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